

Engineered Plastic Characteristics II

Bakelite, Epoxy Glass and Ceramics

☞ For Heat Insulation Plates, see P.1675~1686.

Characteristics of Bakelite, Epoxy Glass and Ceramics

Characteristics of Bakelite Plate

MISUMI's Bakelite Plates are products which can be used as insulating plates for switch board, controller and breaker.

Paper Type is available in natural color and black, and strong Cloth Type is also available.

Bakelite Color (Natural Color) may vary depending on production lot, but does not affect quality.

Characteristics of Epoxy Glass Plate

Compared with paper based bakelite plates and cloth based bakelite plates, MISUMI's epoxy glass plates have higher strength (mechanical strength), and superior heat/moisture resistance.

High Temperature Type has an excellent antistatic property.

Characteristics of Ceramics

Alumina 96 : Excellent in abrasion/insulation/heat resistance, and used for insulating/heat resisting parts in electricity, semiconductors and the other areas. In addition, it has equal or higher bending strength, compared with the common steel, and little elastic deformation.

Steatite : Steatite Ceramics are excellent in insulation and high frequency characteristic and are used as general insulation parts. It is a relatively low-cost material.

Machinable : Excellent machinability. Can be machined into complex forms. Precision finishing. Provides an excellent electric and thermal insulation.

Physical Property Values of Bakelite and Epoxy Glass * For material colors or features, see P951.

Item	Plate	Representative Products					
		Bakelite		Epoxy Glass			
		Paper Type	Cloth Type	Standard	High Temperature		
		P.1001	P.1001	P.1007	P.1007		
Circular Plate	P.1023	P.1023	P.1023	-			
Unit	BLA BLBA	BLSA	EPXA	EPXAR			
Component	Main Base Material	-	Kraft Paper	Cotton	Glass Fiber	Glass Fiber	
	Main Material	-	Phenol Resin	Phenol Resin	Epoxy Resin	Super-insulated Epoxy	
Mechanical Properties	Bending Strength	MPa (kgf/mm ²)	120~180 {12~18}	100~150 {10~15}	310~450 {31~45}	489 (Horizontal) / 553 (Vertical) {51 (Horizontal) / 56 (Vertical)}	
	Compression Strength	Vertical to Lamination	MPa (kgf/mm ²)	250~320 {25~32}	200~250 {20~25}	470~539 {47~53.9}	-
		Horizontal to Lamination	MPa (kgf/mm ²)	170~210 {17~21}	100~150 {10~15}	294~392 {29.4~39.2}	-
	Izod Impact Strength	J/cm	0.2~0.5	0.5~0.7	4.6 or More	-	
	Cleavage Strength	kN	3.9~5.9	6.0~8.0	6.9~10.8	-	
Thermal Characteristics	Recommended Operating Temperature (Note 1)	°C	-50 ~ 100 (130°C 2h Normal)	-50 ~ 100 (140°C 2h Normal)	Ambient Temp. ~ 155	Ambient Temp. ~260 (300°C Normal for 5 min.)	
	Reference - Destructive Temp. (Note 2)	°C	120	140	-	-	
	Expansion Coefficient	°C ⁻¹	1.6x10 ⁻⁴	0.6x10 ⁻⁴	6.05x10 ⁻⁵	6.0x10 ⁻⁵	
	Thermal Conductivity	W/m·K (cal/cm, sec, °C)	0.21 {0.5x10 ⁻³ }	0.38 {0.9x10 ⁻³ }	0.471 {1.125x10 ⁻³ }	0.38 {9.0x10 ⁻⁴ }	
Electric Characteristics	Through Layer Dielectric Breakdown	kV/mm	20~28	12~20	20~30	-	
	Edgewise Withstand Voltage	kV	12~18	8~15	-	-	
	Volume Resistivity	4h/150°C	Ω·cm	3.0x10 ⁹	4.0x10 ⁸	-	-
		100h/25°C/90%RH	Ω·cm	9.0x10 ⁸	5.0x10 ⁷	-	-
	Surface Resistance	Ω	5.0x10 ¹⁰	9.0x10 ⁹	10 ¹³ ~10 ¹⁴	1.0x10 ⁷	
	Insulation Resistance	Ordinary Condition	Ω	10 ¹⁰ ~5x10 ¹¹	5x10 ⁹ ~10 ¹⁰	10 ¹² ~10 ¹⁴	-
After Boiling		Ω	5x10 ⁷ ~10 ⁸	10 ⁸ ~10 ⁹	5x10 ¹⁰ ~10 ¹³	-	
Others	Arc Resistance	sec	-	-	-	-	
	Water Absorption Ratio	%	0.5~1.3	1.6~1.8	0.02~0.03	0.02	
	Specific Gravity	-	1.4	1.4	1.75~1.9	1.95	

☞ Testing method conforms to JIS K6911. ☞ Listed values are for reference, not guaranteed.

(Note 1) "Recommended Operating Temperature" is the temperature under which even a long-term use does not reduce the quality rapidly.

(Note 2) "Destructive Temperature" is the temperature to start carbonization, collapse and melt.

Physical Property Values of Ceramics

Item	Plate	Representative Products			
		P.989	P.989	P.989	P.990
		Circular Plate	P.991	P.991	-
Unit	CEA, PCEA	CCES, PCCES	CEM	CEMN	
Material Name	-	Alumina 96 Al ₂ O ₃ 96%	Steatite MgO, SiO ₂	Machinable SiO ₂ , MgO	Al ₂ O ₃ /Alumina 99 Al ₂ O ₃ 99.7%
Apparent Density	g/cm ³	3.7	2.5	2.5	3.9
Water Absorption Ratio	%	0	0	0	0
Bending Strength	MPa	300	120	94	340
Thermal Conductivity	W/m·k (cal/cm, sec, °C)	18 {4.0x10 ⁻² }	2 {5.0x10 ⁻³ }	1.46	30
Thermal Expansion Coefficient	(20~500°C) x10 ⁻⁶ /°C	7.3	7.4	9.4	7.4
	(20~800°C) x10 ⁻⁶ /°C	8	8.1	12.6	7.9
Melting Point	°C	2050	1557	1200	2000
Safety Operating Temperature	°C	1300	1000	1000	1500
Insulation Resistance	kV/mm	>10	>10	40	>10
Specific Volume Resistivity	Ω·cm	>10 ¹⁴	>10 ¹⁴	>10 ¹⁶	>10 ¹⁵
Dielectric Constant	MHz	9	5.2	6	10
Loss Coefficient	-	10.0x10 ⁴	7.0x10 ⁴	-	-

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Drilling Conditions of the Epoxy Glass

Tool	Circular Cut	Milling	Drilling
	Carbide (K-10)	Carbide (K-10)	Carbide (K-10)
Cutting Speed V (m/min)	Large ~ Small Blades 45~200	Large ~ Small Blades 100~300	Large ~ Small Blades 120~350
Speed (r.p.m.)	Large ~ Small Blades 50~1000	Large ~ Small Blades 300~1000	Ø5 Through 1000 ~ 1500 Ø5 Through 500 ~ 1000
Cutting Depth (mm)	0.3~0.5	0.5~2.0	-
Feed (mm/rev)	0.1~0.2	0.1~0.2	0.1~0.5

☞ The above values are for references only.

Machinable Ceramics Drilling Conditions

Circular Cut	Tool	High-Speed Steel	Carbide
	Carbide (K-10)	High-Speed Steel	Carbide (K-10)
Cutting Speed (m/min)	-	9~15	30~50
Feed (mm/rev)	-	0.05~0.13	-
Cutting Depth (mm)	-	0.5~6	-
Milling	Cutting Speed (m/min)	-	6~11
	Feed (mm/rev)	-	0.05
	Cutting Depth (mm)	-	0.5~5
Note	Revolution Frequency	Revolutions per Minute = Cutting Speed (m/min) / Diameter (mm) x 0.00314	

☞ The above values are for references only.